

# SOT2283-1(SC)

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

22 September 2025

Package information



## 1 Package summary

|                                       |                                                                     |
|---------------------------------------|---------------------------------------------------------------------|
| <b>Terminal position code</b>         | Q (quad)                                                            |
| <b>Package type descriptive code</b>  | FC-PQFN-COL24                                                       |
| <b>Package style descriptive code</b> | FC-PQFN-COL (flip chip - plastic quad flat non-lead - chip on lead) |
| <b>Package body material type</b>     | P (plastic)                                                         |
| <b>Mounting method type</b>           | S (surface mount)                                                   |
| <b>Manufacturer package code</b>      | 98ASA02254D                                                         |

Table 1. Package summary

| Parameter                      | Min | Nom  | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length                 | 4.4 | 4.5  | 4.6 | mm   |
| package width                  | 3.4 | 3.5  | 3.6 | mm   |
| seated height                  | 0.7 | 0.75 | 0.8 | mm   |
| package height                 | 0.7 | 0.75 | 0.8 | mm   |
| nominal pitch                  | -   | 0.5  | -   | mm   |
| actual quantity of termination | -   | 24   | -   |      |



FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

2 Package outline

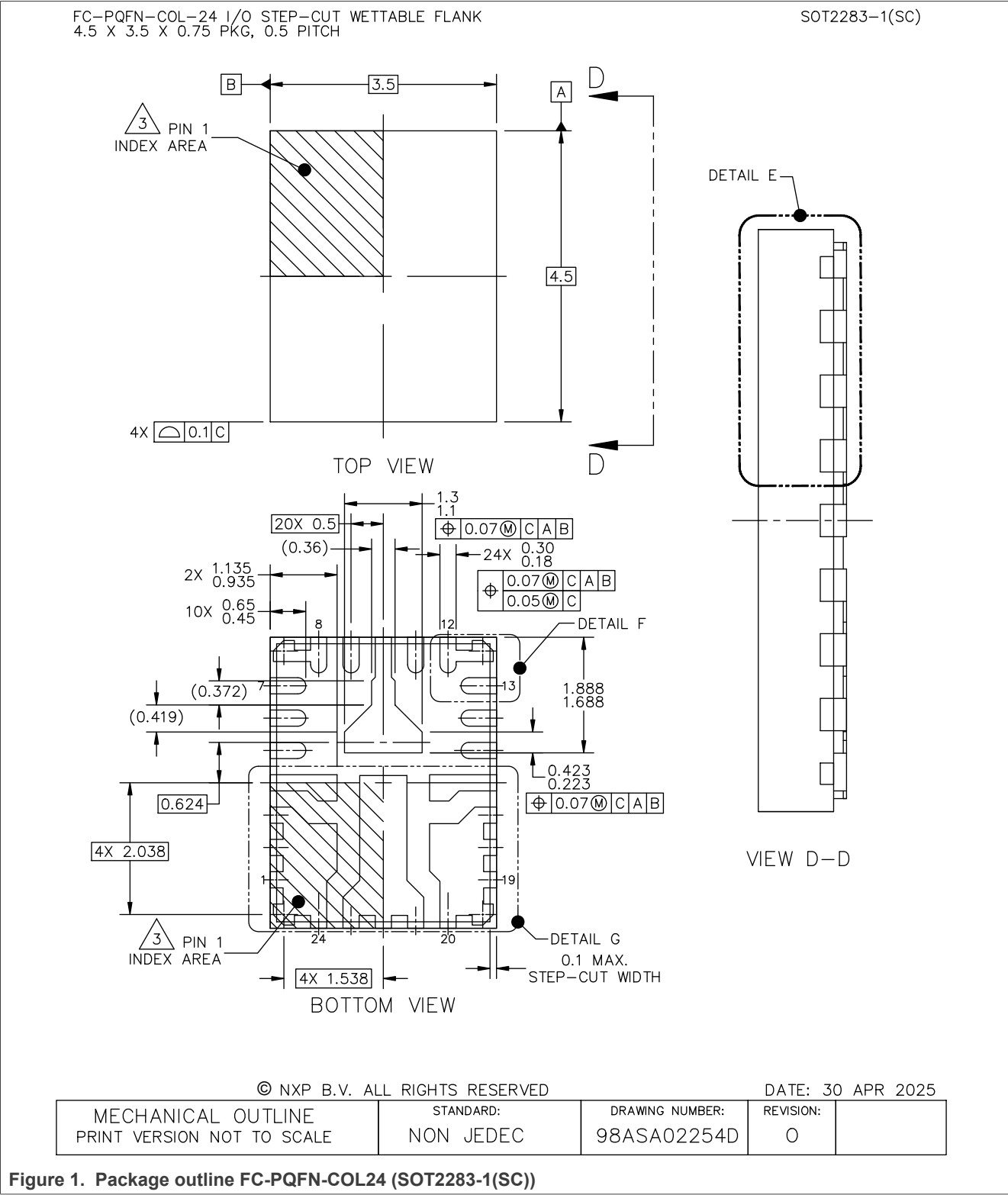
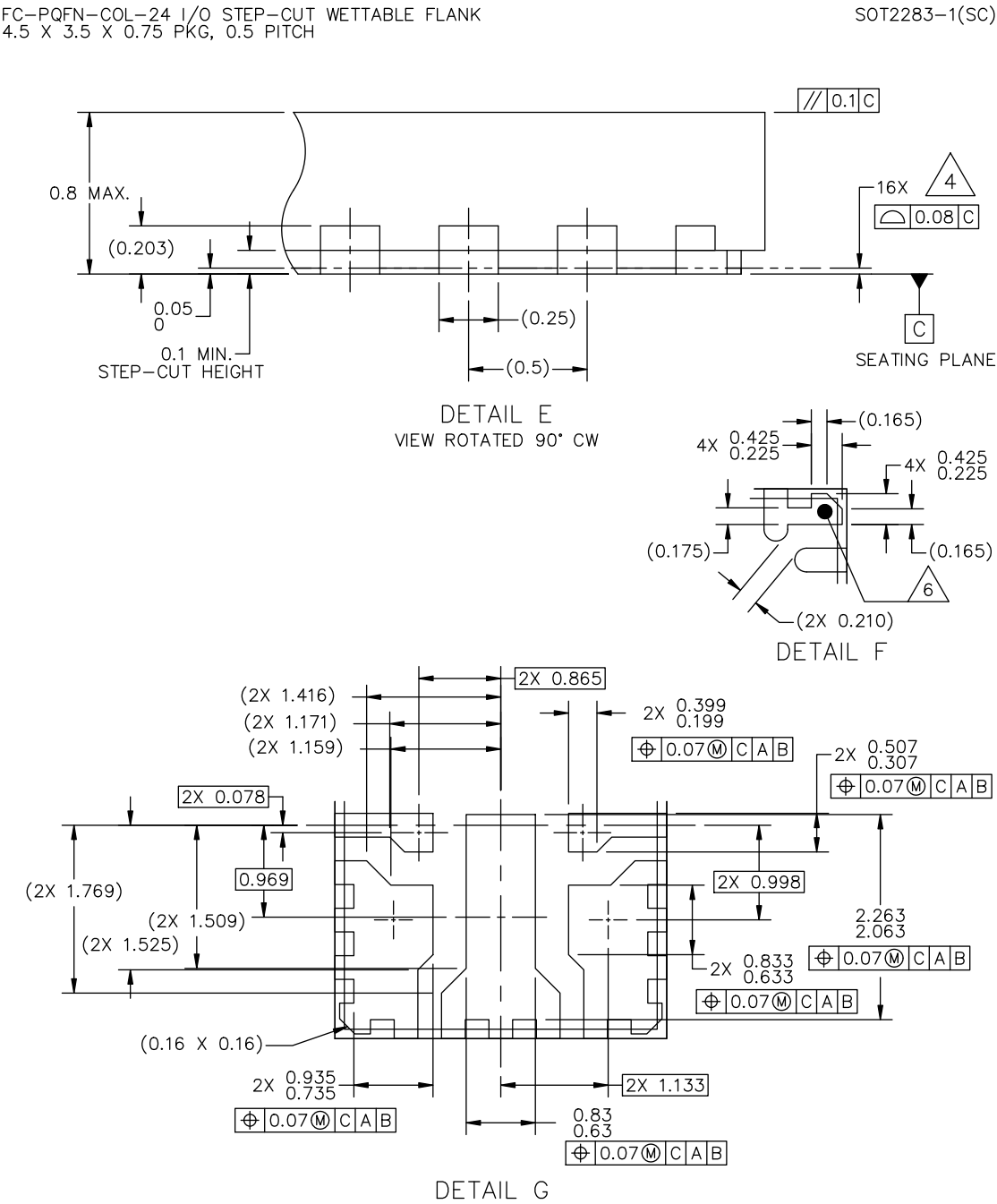


Figure 1. Package outline FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body



|                                                  |                        |                                |                   |  |
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Figure 2. Package outline detail E, F, and G of FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

3 Soldering

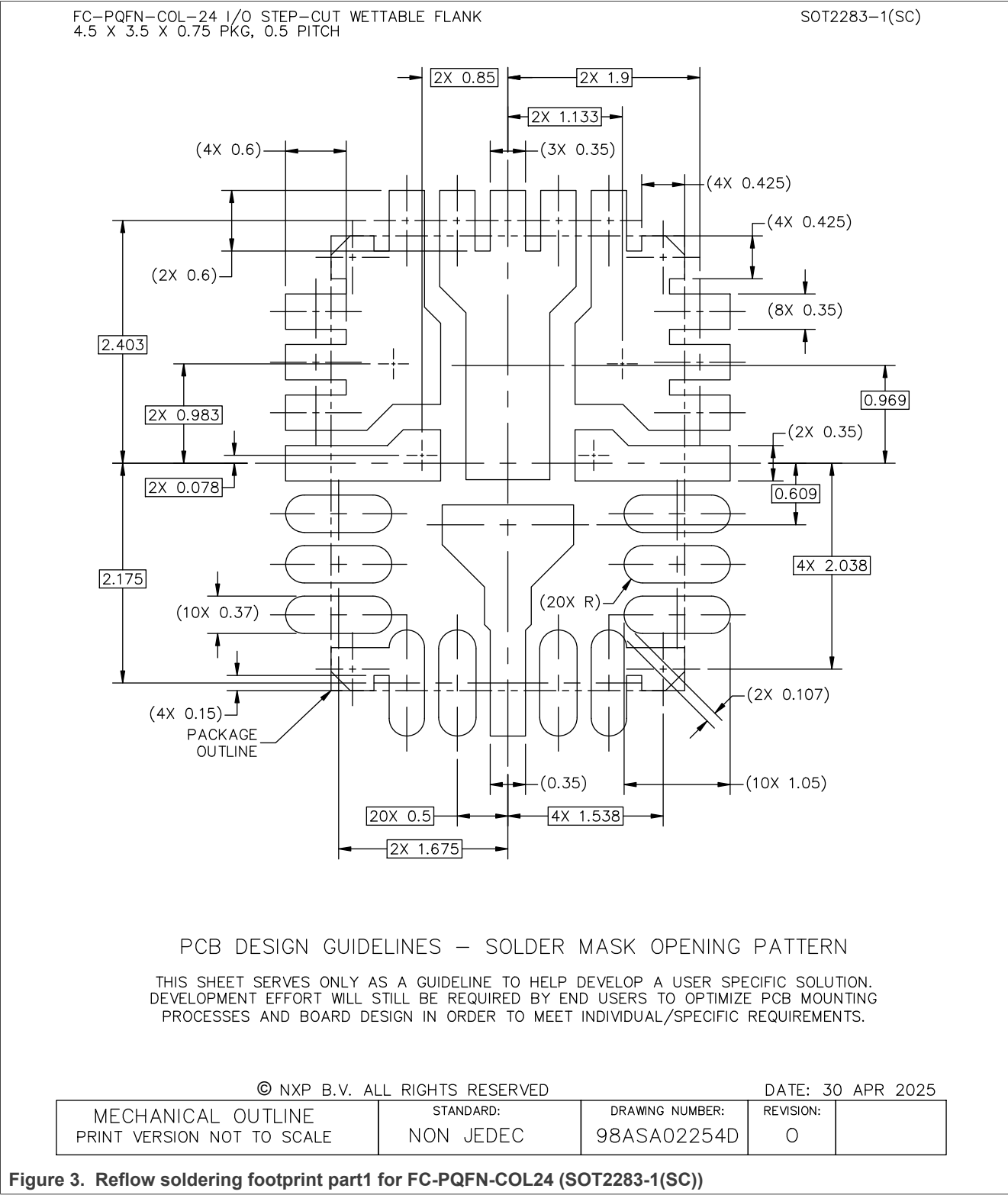
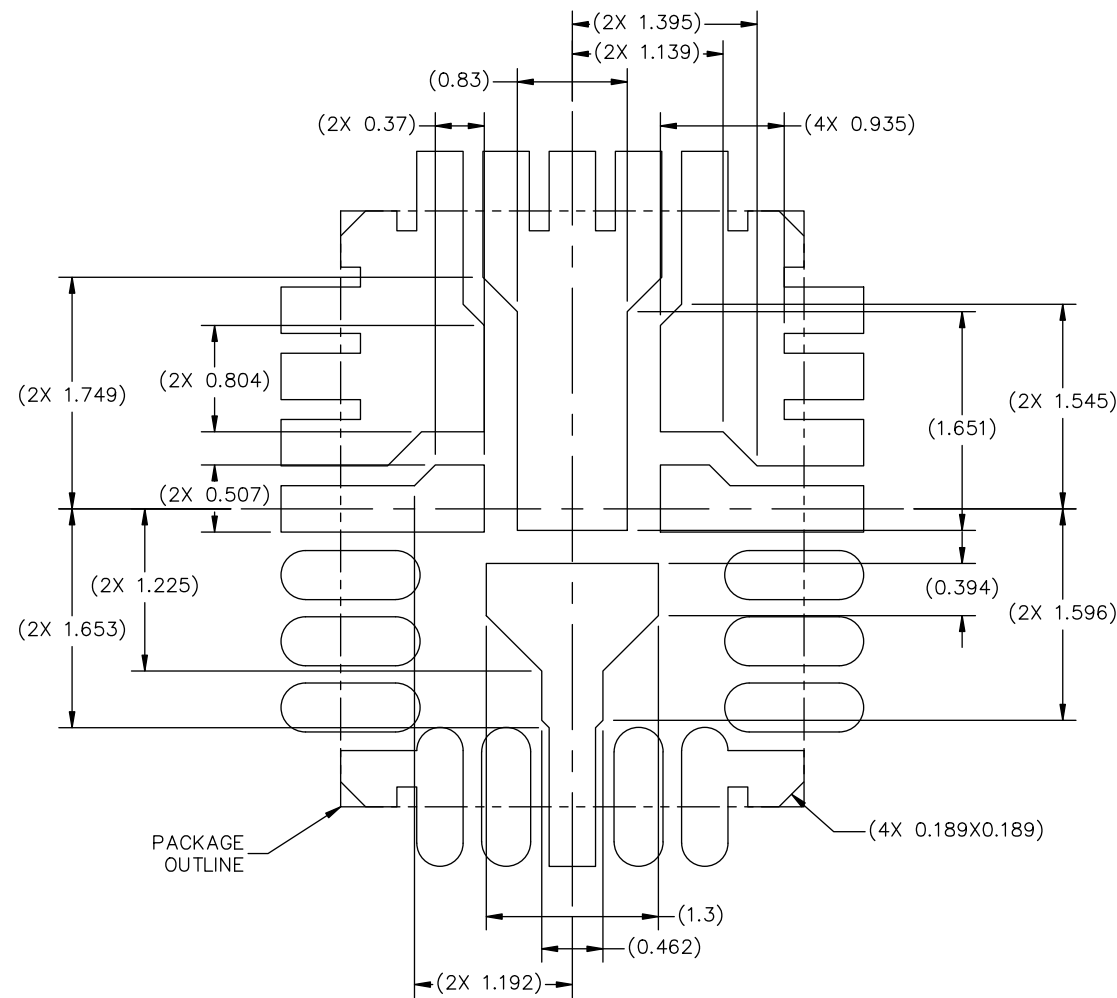


Figure 3. Reflow soldering footprint part1 for FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

FC-PQFN-COL-24 I/O STEP-CUT WETTABLE FLANK  
4.5 X 3.5 X 0.75 PKG, 0.5 PITCH

SOT2283-1(SC)



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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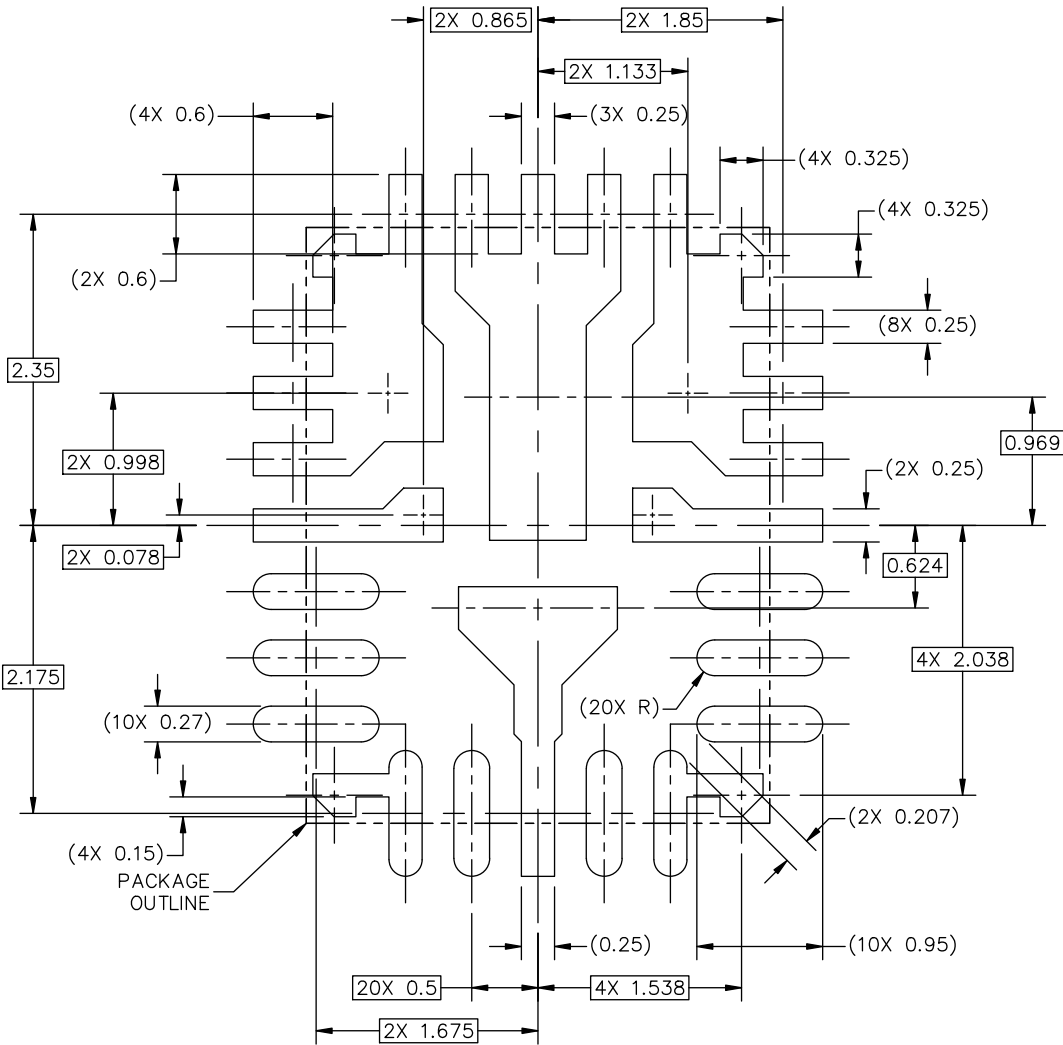
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Figure 4. Reflow soldering footprint part2 for FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

FC-PQFN-COL-24 I/O STEP-CUT WETTABLE FLANK  
4.5 X 3.5 X 0.75 PKG, 0.5 PITCH

SOT2283-1(SC)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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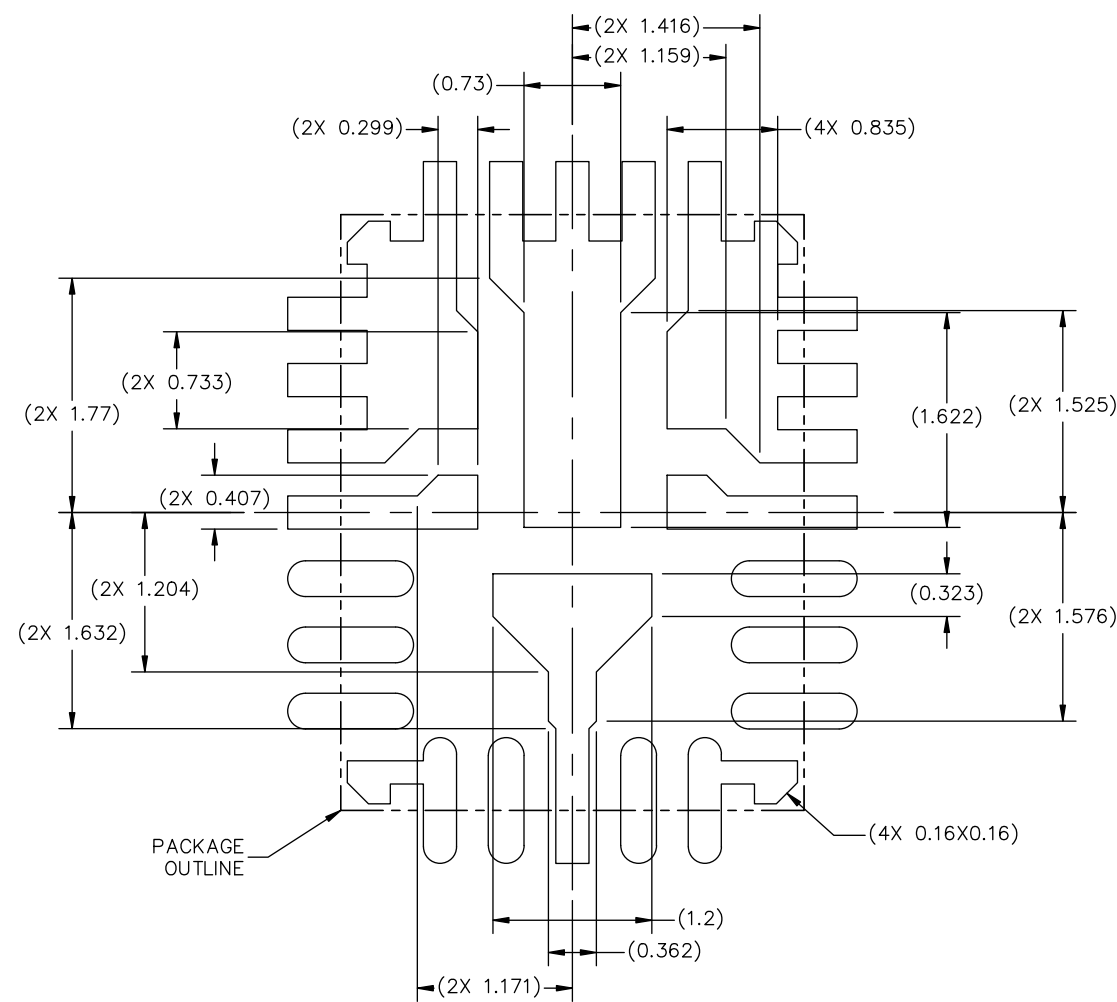
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Figure 5. Reflow soldering footprint part3 for FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

FC-PQFN-COL-24 I/O STEP-CUT WETTABLE FLANK  
4.5 X 3.5 X 0.75 PKG, 0.5 PITCH

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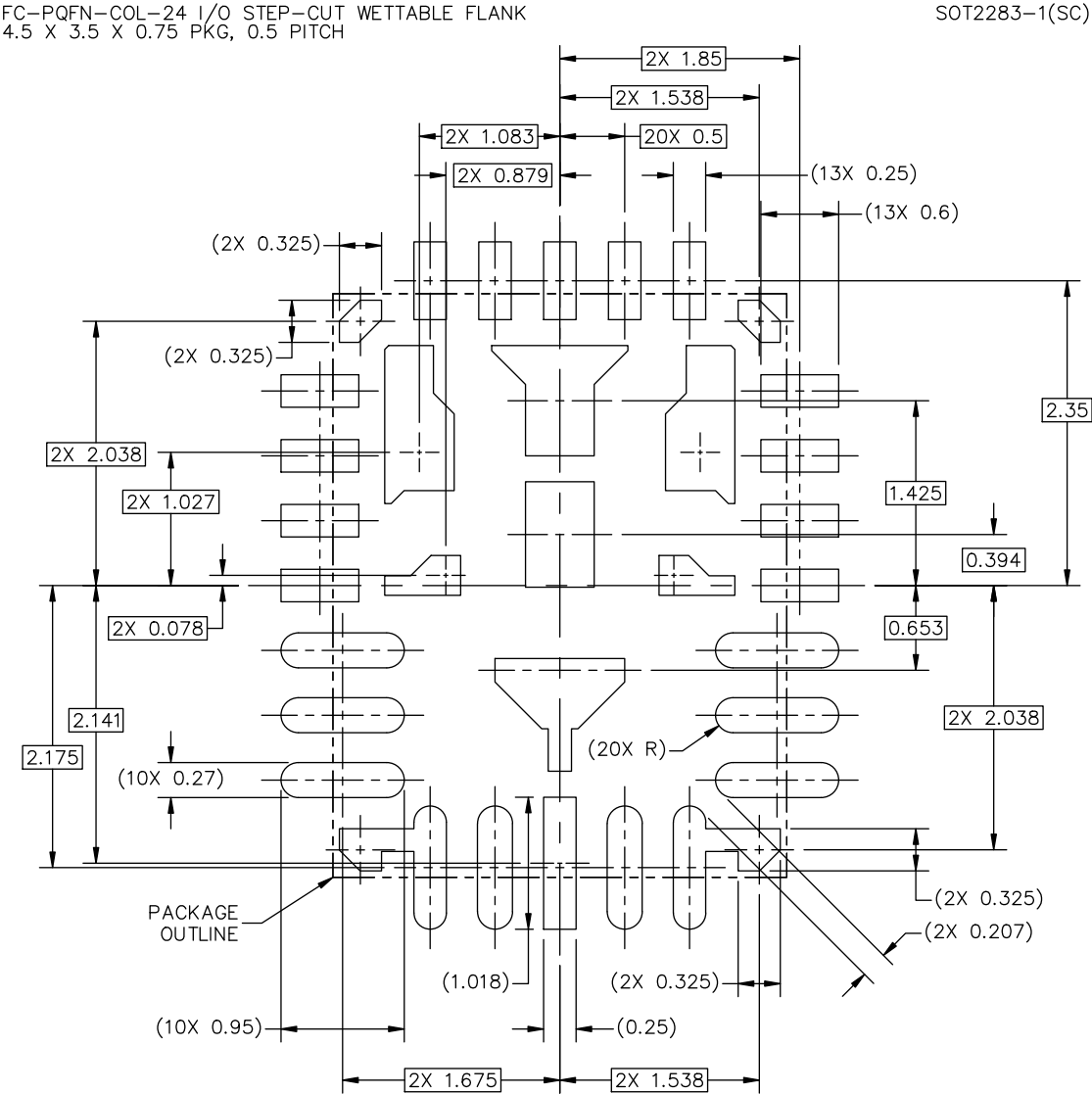
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Figure 6. Reflow soldering footprint part4 for FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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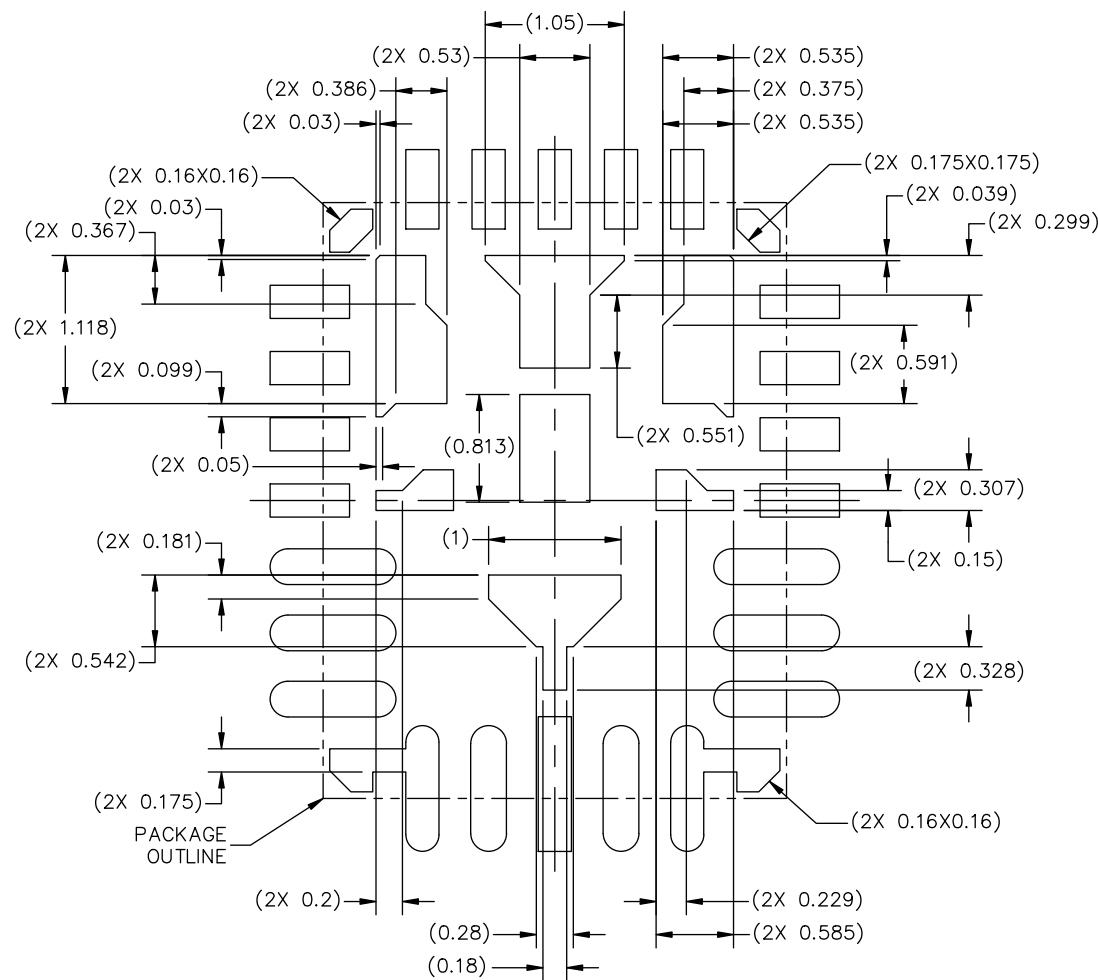
Figure 7. Reflow soldering footprint part5 for FC-PQFN-COL24 (SOT2283-1(SC))



FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

FC-PQFN-COL-24 I/O STEP-CUT WETTABLE FLANK  
4.5 X 3.5 X 0.75 PKG, 0.5 PITCH

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|--------------------------------------------------|------------------------|--------------------------------|----------------|--|

Figure 8. Reflow soldering footprint part6 for FC-PQFN-COL24 (SOT2283-1(SC))

FC-PQFN-COL24, flip chip - plastic quad flat non-lead - chip on lead, 24 terminals, 0.5 mm pitch, 4.5 mm x 3.5 mm x 0.75 mm body

FC-PQFN-COL-24 I/O STEP-CUT WETTABLE FLANK  
4.5 X 3.5 X 0.75 PKG, 0.5 PITCH

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- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
  - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
  - 3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
  - 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
  - 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
  - 6. ANCHORING PADS.

|                                                  |                        |                                |                |  |
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Figure 9. Package outline note FC-PQFN-COL24 (SOT2283-1(SC))

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